GL11/GL21

FEATURES Suitable for manual soldering Good Insulation Excellent Dimensional Stability Cost-effective GL11 Surface Anodic Oxidation Treatment CCL; GL21 Free Surface Anodic Oxidation Treatment CCL

APPLICATIONS

■ LED Lighting etc.

GENERAL PROPERTIES

Item	Test Condition	Unit	Specification	Actual Value
Thermal Conductivity	CPCA-4105-2010	W/m·K	$\lambda < 1.0$	0.6
Heat Resistance	CPCA-4105-2010	K·m2/W	≤2.0×10-4	1.8×10-4
Thermal Stress	288℃ Solder Float	S	288℃≥60	80
Peel Strength	288℃/10s Float	LBS/IN	≥ 6	7
Dielectric Breakdown	AC	KV	≥2	3
Flammability	UL94	/	V-0	ACC

Note:

1. The Dielectric Breakdown value would meet the requirements according to the CPCA

4105-2010 C.8 AC standard.

2. Because of the impact of the flashover and creepage caused by lower creepage distance, the

Dielectric Breakdown value of Al Base PCB will be down. The test should be performed under oil

bath conditions.

Specification:

Thickness: 0.8mm; 1.0mm; 1.2mm; 1.5 mm; 1.6mm; 2.0mm Copper Foil: 18μm; 1oz; 1.5oz; 2oz; 3oz; 28μm

Size: 1000x1200mm; 1050x1250mm; Specifical size can be afford independently.